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NO. 465 P. 3

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Dated: July 28, 2005

Signature: Valerie Cohen

(Valerie Cohen)

REPLY UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER 2800  
Docket No.: 495152000610  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Hui WANG et al.

Application No.: 10/664,783

Art Unit: 2823

Filed: September 16, 2003

Examiner: M. Estrada

For: ELECTROPOLISHING METAL LAYERS ON  
WAFERS HAVING TRENCHES OR VIAS  
WITH DUMMY STRUCTURES

**AMENDMENT UNDER 37 CFR 1.116**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This is in response to the final Office Action dated May 26, 2005 (Part of Paper No./Mail Date 20050517), for which a response is due on August 26, 2005. Accordingly, this response is timely filed. Additionally, this response is filed within two months of the mailing date of the Final Office Action and therefore qualifies for expedited review. Reconsideration and allowance of the pending claims in light of the remarks presented herein are respectfully requested.

SF-1973840